**Material Characterization** 

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Metrology  $\overline{\mathbf{O}}$ Analytical technology Foreign Materials **Depth Profile** Depth Directi Foreign Partic Glow Discharge Optical Emission Spectrometry Micro X-Ray analyzer Spectroscopic ellipsometry Cathodoluminescence **GD-Profiler2** Raman spectroscopy Glow discharge emission XGT-9000 Expert · Rapid depth direction element analysis · No ultra high vacuum required Photoluminescence X-ray Fluorescence · A rapid elemental analysis of depth from Light element analysis from B (Boron) H(Hydrogen) to U(Uranium)) Transmittance X-ray for visualizing inside components **Career Lifetime** Career Life · Film thickness analysis of metal thin film Carrier life time evaluation by time resolved PL anaysis DeltaFlex X Ray transmittance imag · Carrier life time evaluation by time resolved PL · A wide range of wavelength for light source Composite imag • Time resolved PL analysis from picoseconds to a few seconds (Elemental mapping + X Ray transmittance) Elemental mapping image USB Memory Film Thickness / Bandgap Spectroscopic ellipsometer **UVISEL Plus** · Analysis of film thickness, refractive index, and extinction coefficient of ultra thin film In Situ measurement Stress **Defects / Impurities** Befittin Crystal Defe Micro Raman Spectroscopy **AFM Raman integration** Photoluminescence measurement system Cathodoluminescence measuring system LabRAM HR Evolution Nano **HORIBA CLUE Series** LabRAM HR Evolution SMS Integrated to a window • The highest stress resolution One AFM and one Raman · Upgrade microscope to Spectroscopic microscope system! port of SEM Mapping measurement can be done nm order first spacial up to 12 inch wafers Raman, PL and Time resolved PL Coupling with Raman analysis resolution measurement capabilities Cryostat available Upgradable for a wide area measurement No sample movement required · Mapping measurement available